JET PROPULSION LABORATORY

INTEROFFICE MEMORANDUM

TES DFM #980-4.1.1 10/13/00

TO: Design File

FROM: Ed Miller

SUBJECT: Engineering Data Interface (EDIF) #01 HRCR Completion

REF: TES Design File Memo #937-4.2.1

The HRCR for the TES Engineering Data Interface (EDIF) #01 Assembly, ref. des. 2045ED01, was completed on 07/13/2000.

All action items generated at that review have now been closed.

A copy of the completed and signed HRCR form is attached, and is included with the End Item Data Package (EIDP). A hard copy of the EIDP may be found in the TES project files, in the I&T files, and in the JPL Vellum Files.

Electronic copies of all TES EIDP's are being made by optically scanning the packages. These electronic copies will be stored on compact disks which will be available from the TES project office upon completion of the scanning.

cc: TES Design File

TES Hardware Requirements Certification Review

Assembly/Subsystem			Cognizant Engineer				Phone	Section			Date		
TES C& DH/EDIF				ck V	Voc	oddell	393-3914 344			And the second seco	07/13/2000		
Ref. Des.	Drawing No.	Dwg. Rev.	Serial No.			Nomenclature		Fi	nal IR	Op. Time Cycles (i		Mass (Kg)	
2045ED 01	10179420	A	FLT001			TES Electronic A	ssembly, EDIF	90	900756 150 Min. 2 cycles		0.708 w/o conformal coat		
Check applicable answer and give necessary explanation in remarks column			Y	N o	N / A	Remarks		Data	Data Attachments		Signature Approval & Date		
Are all drawings and specifications complete, approved, released and frozen?			8	0	۵		18. Latest Top Assembly Drawings ☑ Attached ☐ None			Cognizant Engineer			
2. Do the released drawings and specifications reflect all approved changes?			8		0				19. List of open ECRs ☐ Attached ☐ None		Coddizant PEM 10/211		
Is hardware identical to other hardware delivered? If no, provide difference list.			8	0	۵	01 & 02 are identical		20. W	20. Walvers Attached S None		Materials Engineer Lucky Fareky		
Does the hardware meet the requirement of its FRs, specifications, waivers and/or ICDs ? If no, provide difference list. (See Item 28 for reference.)			8	0	۵			DA	21. Open MRBs ☐ Attached 図None		OA English	- Kenny	
Have all discrepancies and MRBs been dispositioned and agreed to by Engineering/ QA?			8	0	۵			22. Open Problem Logs & P/FRs ☐ Attached		Misson As Hydrice Mgr.			
Has complete as-built list information been submitted to PDMG?			8	0	n			on s	i. Open Problem Logs & P/FRs is sim. H/W and/or related S/W Altached		System Englished		
7. Are required design analyses complete, up to date, approved and archived? Attack identifying list per item 29.			8	0	0			Auth	. Signed Environmental Test uthorization & Summary (ETAS) Attached None		Integration & Test Mar. Instrument Appropriate (Instrument Appropriate (Instru		
Have all required environmental qualification tests & analyses called for in D-13144, Table 5.2 been completed?			8	0	0			Shed	i. Assy/ Subsystem Power Data heet Alteched			Tille	
Is all required assembly and/or subsystem level functional testing completed?			8	0	0			☐ Attached ⊠None 27. Operational Con-			Other?		
10. Have applicable telemetry calibration data been submitted to the System Engineer? 11. Have all required single point failure actions been taken?				0	8			stra	ints/idiosynd litached 🔯	rasies None	Other		
			0	0	8			28. Requirements Verification Matrix (reference Item 4) ☑ Attached ☐ None 29. Design analyses completed,			Other		
12. Have all required mass data been submitted?			8	0	0			app		lived (per item 7)	Other		
Have all stress, corrosion & flammable material requirements been met?			2		0						Other		
14. Have all piece parts, processes and materials been approved by JPL?			8	0	0				*		Other		
15. Has hardware been baked out, cleaned and met all contamination control requirements?			0	189	0	Not baked out yet					Other		
16. Are all required shipping containers, shipping procedures, special handling procedures, AHSE and SE ready?			8	0	0						Other		
17. is this hardware acceptable for flight?			0	8	6		n into integrated Electronics Module or bake out.				Other		